

**1.6mΩ, 30V, N-Channel Power MOSFET**
**SRT03N016L**
**General Description**

The Sanrise SRT03N016L is a high voltage power MOSFET, fabricated using advanced super junction technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and outstanding efficiency.

The SRT03N016L break down voltage is 30V and it has a high rugged avalanche characteristics. The SRT03N016L is available in PDFN5\*6 package.

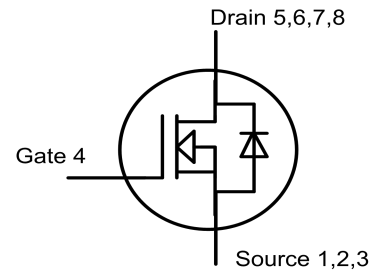
**Symbol**


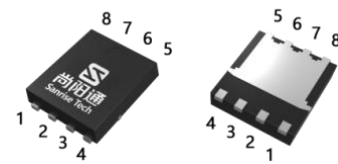
Figure 1 Symbol of SRT03N016L

**Features**

- Ultra Low  $R_{DS(ON)} = 1.35m\Omega @ V_{GS} = 10V$ .
- Ultra Low Gate Charge,  $Q_g = 48.2nC$  typ.
- Fast switching capability
- Robust design with better EAS performance
- Non-automotive Qualified

**Application**

- Server / Telecom
- High Power Supply, such as DCDC converter
- Motor Driver, such as E-Tools
- BMS

**Package Type**


PDFN5\*6

Figure 2 Package Types of SRT03N016L

**Ordering Information**

|                |  |                 |
|----------------|--|-----------------|
| SRT03N016L□□-□ |  |                 |
| Circuit Type   |  | E: Lead Free    |
| Package        |  | G: Green        |
| D56: PDFN5*6   |  | Blank: Tube     |
|                |  | TR: Tape & Reel |

| Package | Part Number       | Marking ID     | Packing Type |
|---------|-------------------|----------------|--------------|
| PDFN5*6 | SRT03N016LD56TR-G | SRT03N016LD56G | Tape & Reel  |

## Absolute Maximum Ratings

| Parameter                                           |                           | Symbol          | Rating     | Unit             |
|-----------------------------------------------------|---------------------------|-----------------|------------|------------------|
| Drain-Source Voltage                                |                           | $V_{DSS}$       | 30         | V                |
| Gate-Source Voltage                                 |                           | $V_{GSS}$       | $\pm 20$   | V                |
| Continuous Drain Current                            | $T_C = 25^\circ\text{C}$  | $I_D$           | 163        | A                |
|                                                     | $T_C = 100^\circ\text{C}$ |                 | 103        |                  |
| Pulsed Drain Current (Note 2)                       |                           | $I_{DM}$        | 652        | A                |
| Power Dissipation ( $T_C = 25^\circ\text{C}$ )      |                           | $P_D$           | 90         | W                |
| Avalanche Destructive Energy, Single Pulse (Note 4) |                           | $E_{AS\_Limit}$ | 324        | mJ               |
| Avalanche Energy, Single Pulse (Note 3)             |                           | $E_{AS}$        | 56         | mJ               |
| Avalanche Current, Repetitive (Note 2)              |                           | $I_{AR}$        | 15.0       | A                |
| Operating Junction Temperature                      |                           | $T_J$           | 150        | $^\circ\text{C}$ |
| Storage Temperature                                 |                           | $T_{STG}$       | -55 to 150 | $^\circ\text{C}$ |
| Lead Temperature (Soldering, 10 sec)                |                           | $T_{LEAD}$      | 260        | $^\circ\text{C}$ |

Note:

1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.  
Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating: Pulse width limited by maximum junction temperature
3.  $I_{AS} = 15.0\text{A}$ ,  $V_{DD} = 15\text{V}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$
4.  $I_{AS\_Limit} = 36.0\text{A}$ ,  $V_{DD} = 15\text{V}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$

## Thermal Characteristics

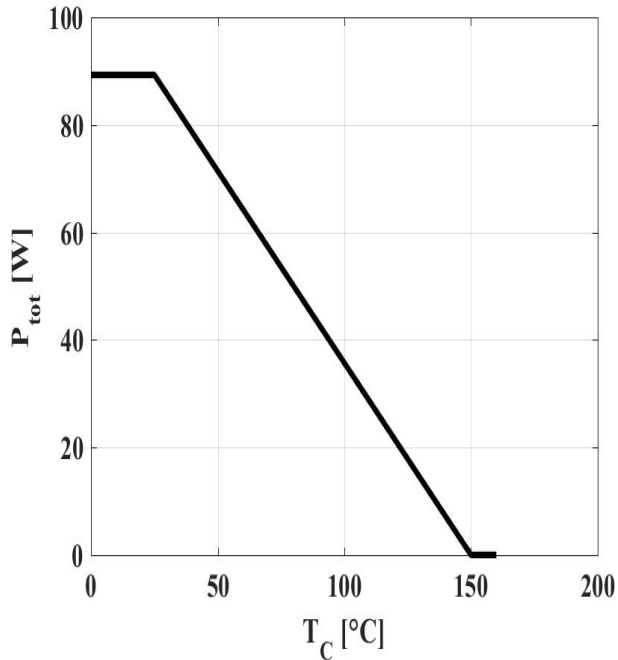
| Parameter                               | Symbol     | Min | Typ  | Max | Unit                      |
|-----------------------------------------|------------|-----|------|-----|---------------------------|
| Thermal Resistance, Junction-to-Case    | $R_{thJC}$ |     | 0.65 | 1.4 | $^\circ\text{C}/\text{W}$ |
| Thermal Resistance, Junction-to-Ambient | $R_{thJA}$ |     |      | 62  |                           |

**1.6m $\Omega$ , 30V, N-Channel Power MOSFET**
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**Electrical Characteristics**
 $T_J = 25^\circ\text{C}$ , unless otherwise specified.

| Parameter                          |         | Symbol               | Test Conditions                                                                         | Min | Typ  | Max  | Unit |
|------------------------------------|---------|----------------------|-----------------------------------------------------------------------------------------|-----|------|------|------|
| Statistic Characteristics          |         |                      |                                                                                         |     |      |      |      |
| Drain-Source Breakdown Voltage     |         | BV <sub>DSS</sub>    | V <sub>GS</sub> =0V, I <sub>D</sub> =250uA                                              | 30  |      |      | V    |
| Zero Gate Voltage Drain Current    |         | I <sub>DSS</sub>     | V <sub>DS</sub> =30V, V <sub>GS</sub> =0V                                               |     |      | 1    | uA   |
| Gate-Body Leakage Current          | Forward | I <sub>GSSF</sub>    | V <sub>GS</sub> =20V, V <sub>DS</sub> =0V                                               |     |      | 100  | nA   |
|                                    | Reverse | I <sub>GSSR</sub>    | V <sub>GS</sub> =-20V, V <sub>DS</sub> =0V                                              |     |      | -100 |      |
| Gate Threshold Voltage             |         | V <sub>GS(TH)</sub>  | V <sub>DS</sub> =V <sub>GS</sub> ,<br>I <sub>D</sub> =0.25mA                            | 1.0 | 1.6  | 2.2  | V    |
| Static Drain-Source On-Resistance  |         | R <sub>DS(ON)</sub>  | V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A                                              |     | 1.95 | 2.7  | mΩ   |
| Static Drain-Source On-Resistance  |         | R <sub>DS(ON)</sub>  | V <sub>GS</sub> =10V, I <sub>D</sub> =50A                                               |     | 1.35 | 1.6  | mΩ   |
| Gate Resistance                    |         | R <sub>G</sub>       | f=1MHz, Open Drain                                                                      |     | 1.3  |      | Ω    |
| Dynamic Characteristics            |         |                      |                                                                                         |     |      |      |      |
| Input Capacitance                  |         | C <sub>ISS</sub>     | V <sub>DS</sub> =15V, V <sub>GS</sub> =0V,<br>f=1MHz                                    |     | 3.6  |      | nF   |
| Output Capacitance                 |         | C <sub>OSS</sub>     |                                                                                         |     | 800  |      | pF   |
| Reverse Transfer Capacitance       |         | C <sub>RSS</sub>     |                                                                                         |     | 180  |      | pF   |
| Turn-on Delay Time                 |         | t <sub>d(on)</sub>   | V <sub>DD</sub> =15V, I <sub>D</sub> =50A<br>R <sub>G</sub> =1.6Ω, V <sub>GS</sub> =10V |     | 12   |      | ns   |
| Rise Time                          |         | t <sub>r</sub>       |                                                                                         |     | 9    |      |      |
| Turn-off Delay Time                |         | t <sub>d(off)</sub>  |                                                                                         |     | 50   |      |      |
| Fall Time                          |         | t <sub>f</sub>       |                                                                                         |     | 9    |      |      |
| Gate Charge Characteristics        |         |                      |                                                                                         |     |      |      |      |
| Gate to Source Charge              |         | Q <sub>gs</sub>      | V <sub>DD</sub> =15V, I <sub>D</sub> =50A<br>V <sub>GS</sub> =0 to 10V                  |     | 6.6  |      | nC   |
| Gate to Drain Charge               |         | Q <sub>gd</sub>      |                                                                                         |     | 6.2  |      |      |
| Gate Charge Total                  |         | Q <sub>g</sub>       |                                                                                         |     | 48.2 |      |      |
| Gate Plateau Voltage               |         | V <sub>plateau</sub> |                                                                                         |     | 2.8  |      | V    |
| Reverse Diode Characteristics      |         |                      |                                                                                         |     |      |      |      |
| Drain-Source Diode Forward Voltage |         | V <sub>SD</sub>      | V <sub>GS</sub> =0V, I <sub>SD</sub> =50A                                               |     | 0.81 | 1.1  | V    |
| Reverse Recovery Time              |         | t <sub>rr</sub>      | V <sub>R</sub> =15V, I <sub>F</sub> =50A                                                |     | 31   |      | ns   |
| Reverse Recovery Charge            |         | Q <sub>rr</sub>      | dI <sub>F</sub> /dt=100A/us                                                             |     | 79   |      | nC   |

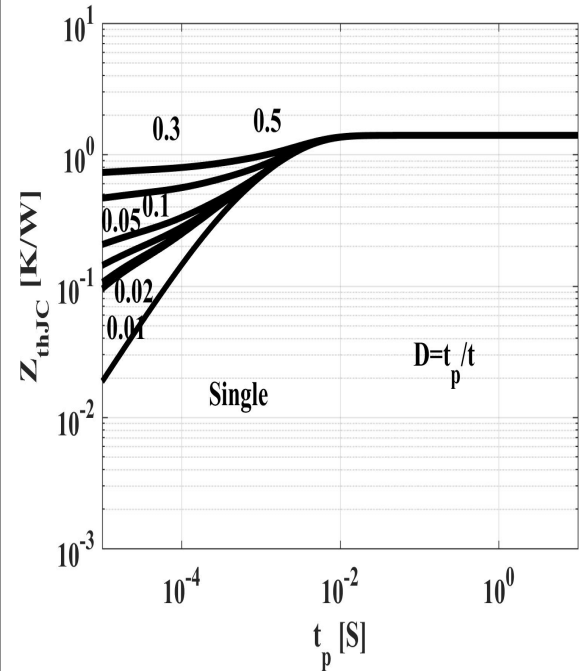
**Typical Performance Characteristics**

Figure 3: Power Dissipation



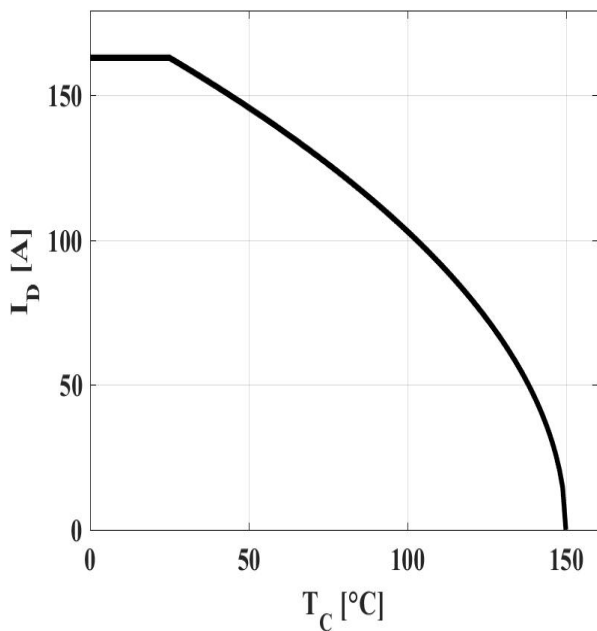
$$P_{tot} = f(T_c)$$

Figure 4: Max. Transient Thermal Impedance



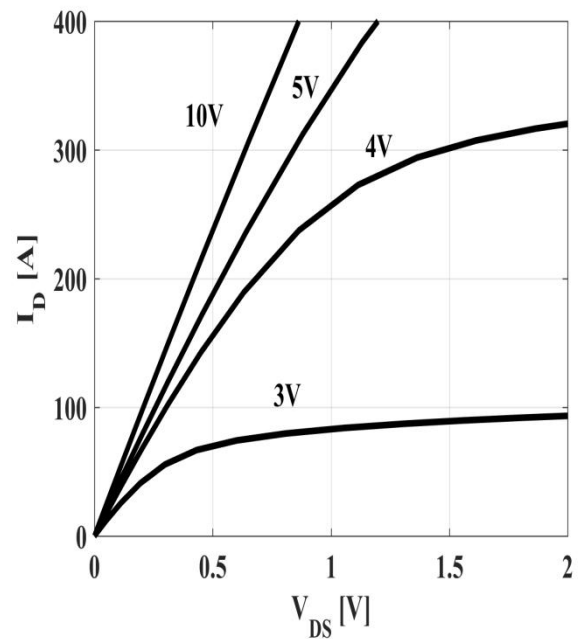
$$Z_{(th)JC} = f(t_p); \text{ parameter: } D = t_p/T$$

Figure 5: Drain Current

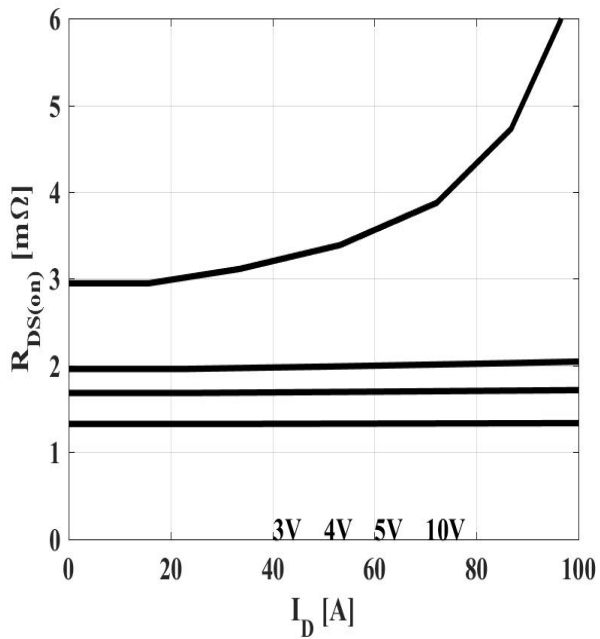
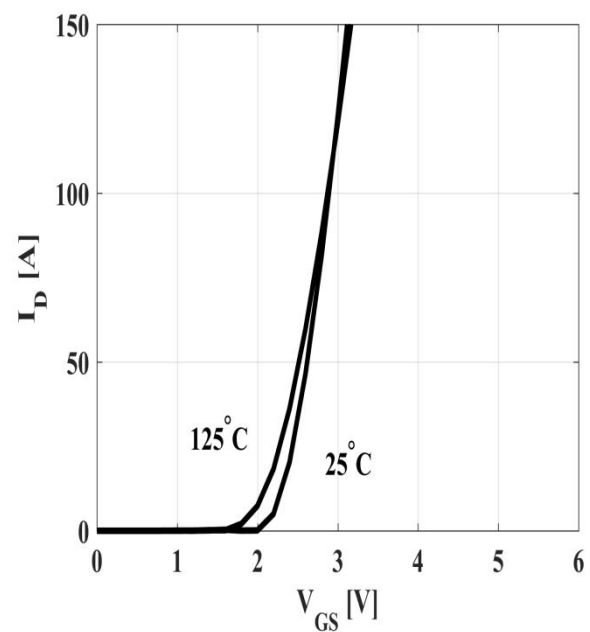
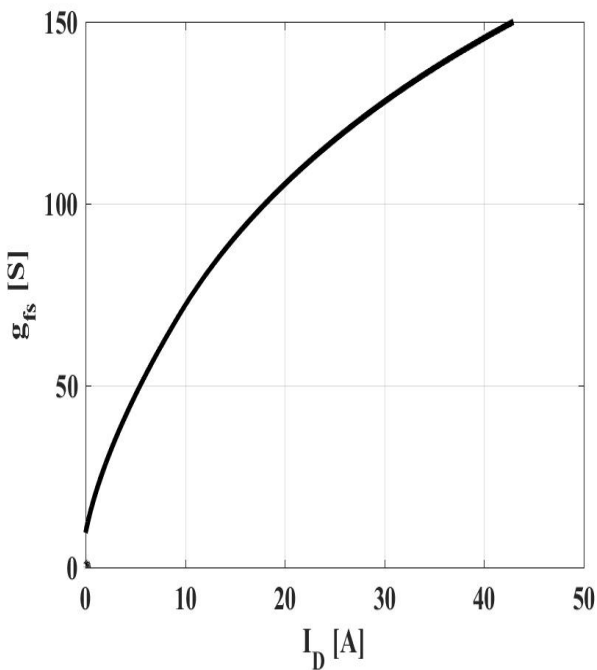
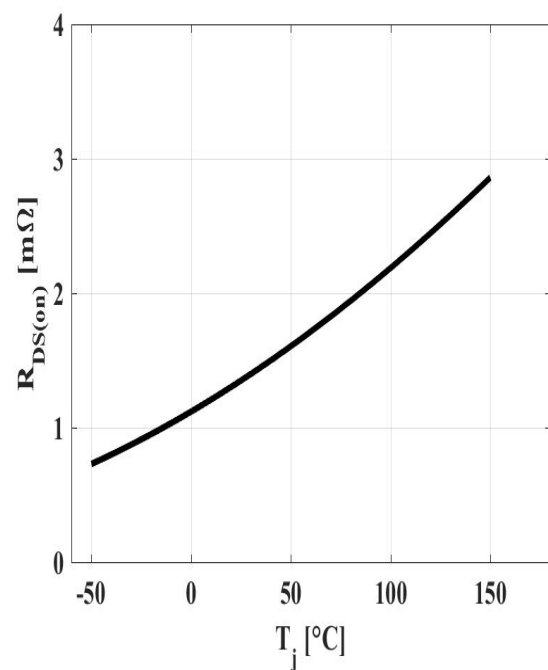


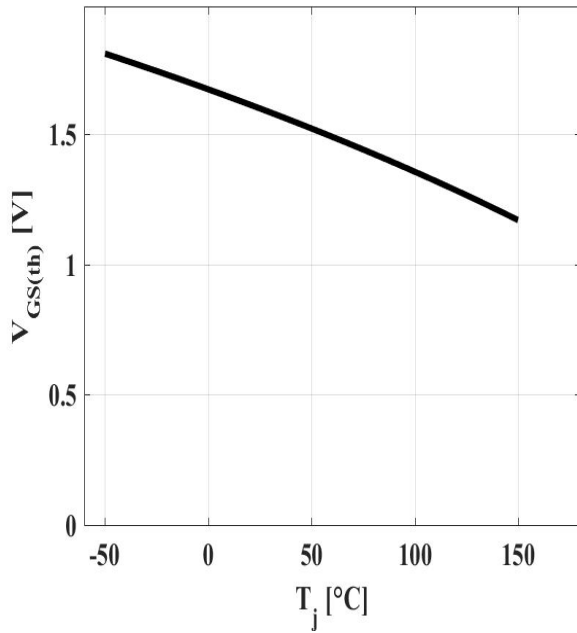
$$I_D = f(T_c); V_{GS} \geq 10V$$

Figure 6: Typ. Output Characteristics

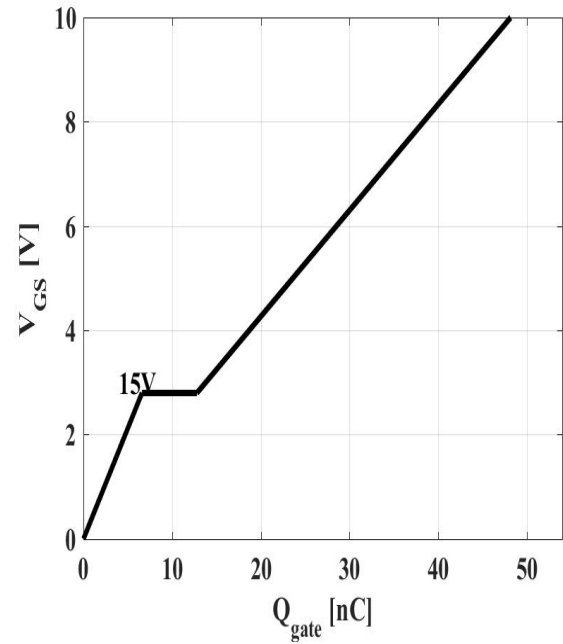


$$I_D = f(V_{DS}); T_j = 25^\circ C; \text{ parameter: } V_{GS}$$

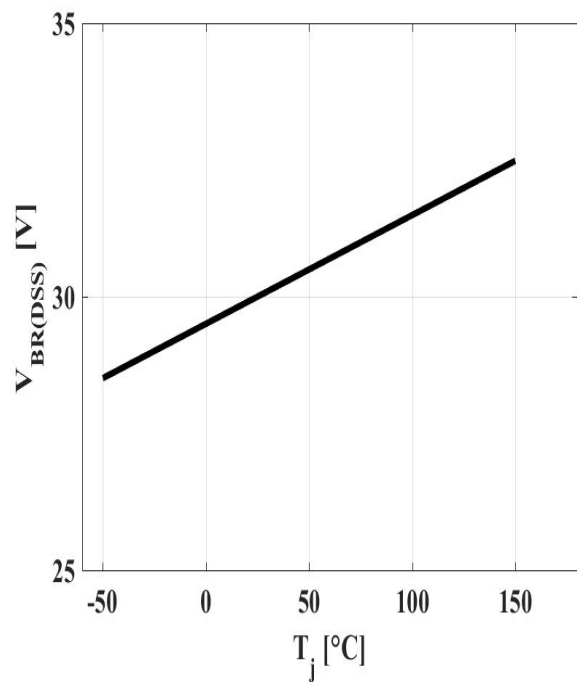
**1.6mΩ, 30V, N-Channel Power MOSFET**
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**Figure 7: Typ. Drain-Source On-State Resistance**

 $R_{DS(ON)} = f(I_D)$ ;  $T_j = 25^\circ\text{C}$ ; parameter:  $V_{GS}$ 
**Figure 8: Typ. Transfer Characteristics**

 $I_D = f(V_{GS})$ ;  $|V_{DS}| > 2|I_D|R_{DS(on)max}$ ; parameter:  $T_j$ 
**Figure 9: Typ. Forward Transconductance**

 $g_{fs} = f(I_D)$ ;  $T_j = 25^\circ\text{C}$ 
**Figure 10: Typ. Drain-Source On-State Resistance**

 $R_{DS(ON)} = f(T_j)$ ;  $I_D = 50\text{A}$ ;  $V_{GS} = 10\text{V}$

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**Figure 11: Typ. Gate Threshold Voltage**


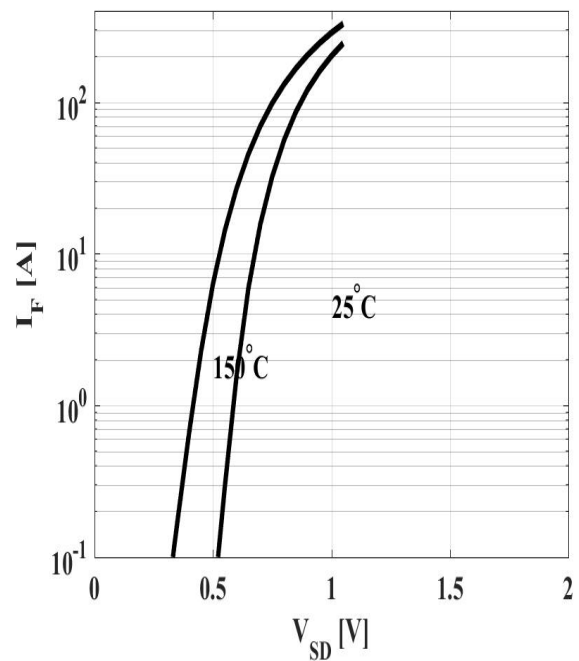
$$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}; I_{DS} = 250\mu A$$

**Figure 12: Typ. Gate Charge**


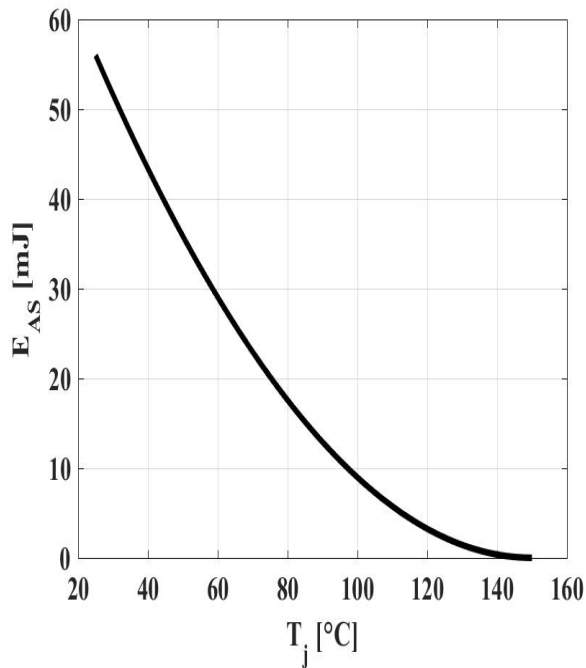
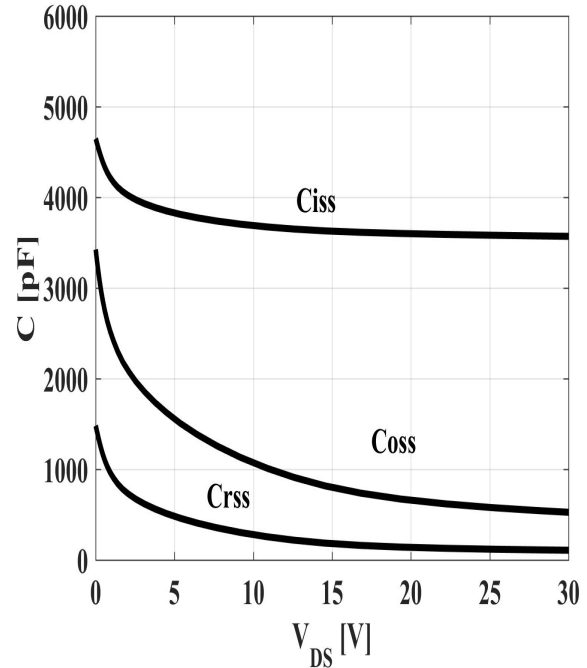
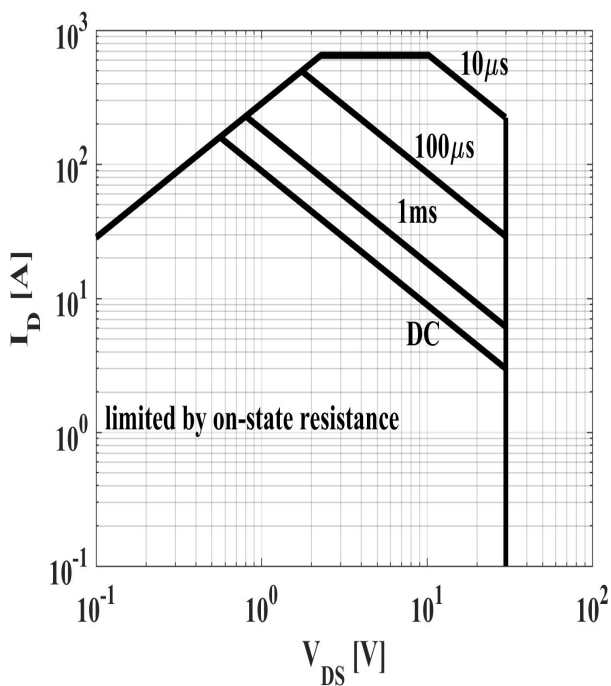
$$V_{GS} = f(Q_{gate}), I_D = 50A \text{ pulsed}$$

**Figure 13: Drain-Source Breakdown Voltage**


$$V_{BR(DSS)} = f(T_j); I_D = 1mA$$

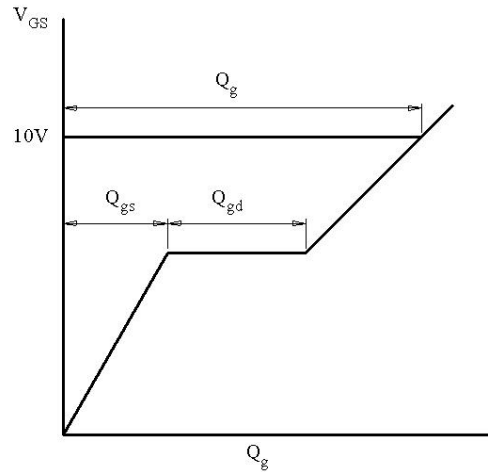
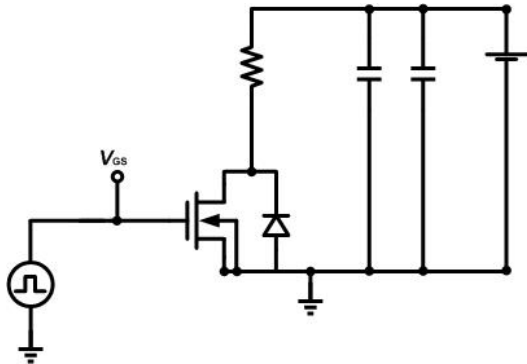
**Figure 14: Forward Characteristics of Reverse Diode**


$$I_F = f(V_{SD}); \text{parameter: } T_j$$

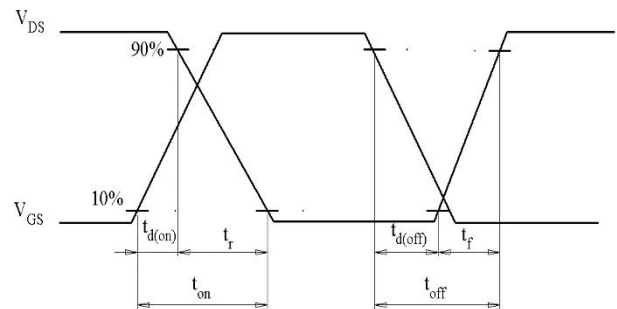
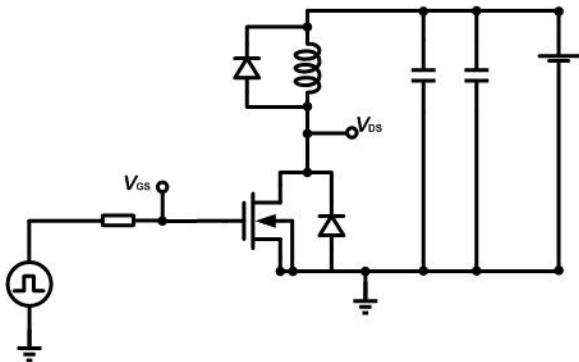
**1.6mΩ, 30V, N-Channel Power MOSFET**
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**Figure 15: Avalanche Energy**

 $E_{AS}=f(T_j)$ ;  $I_D=15.0A$ ;  $V_{DD}=15V$ 
**Figure 16: Typ. Capacitances**

 $C=f(V_{DS})$ ;  $V_{GS}=0$ ;  $f=1MHz$ 
**Figure 17: Safe Operating Area**

 $I_D=f(V_{DS})$ ;  $T_C=25^{\circ}C$ ;  $V_{GS}>7V$ ; parameter:  $t_p$

## Test Circuits

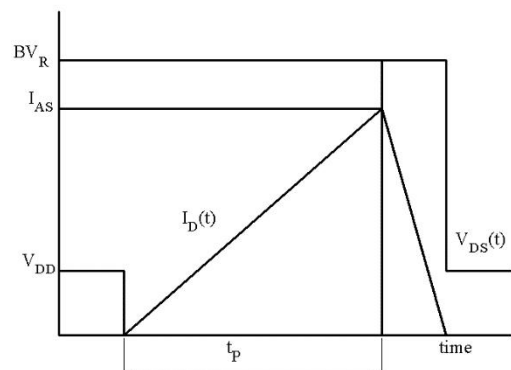
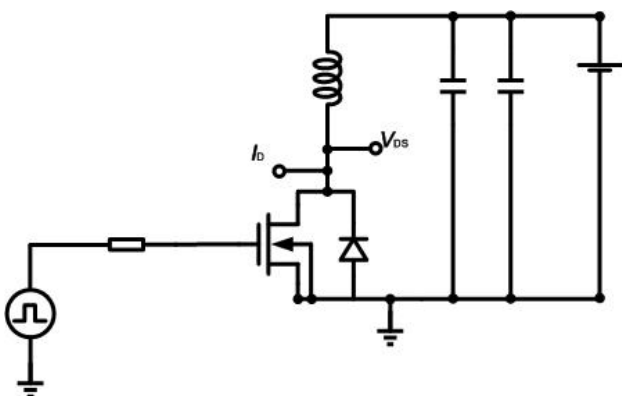
### 1. Gate Charge Test Circuit & Waveform



### 2. Switch Time Test Circuit

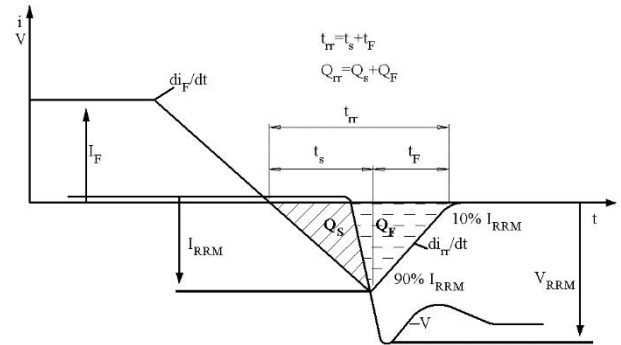
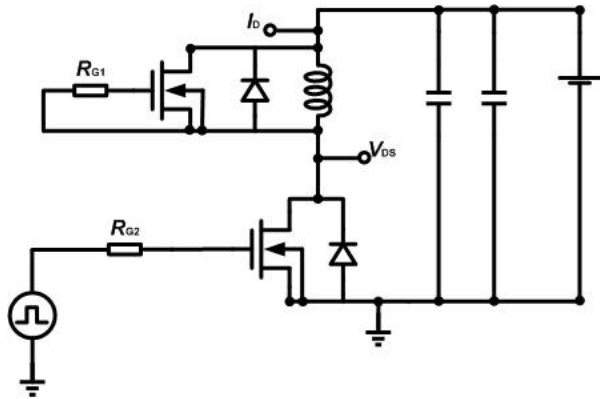


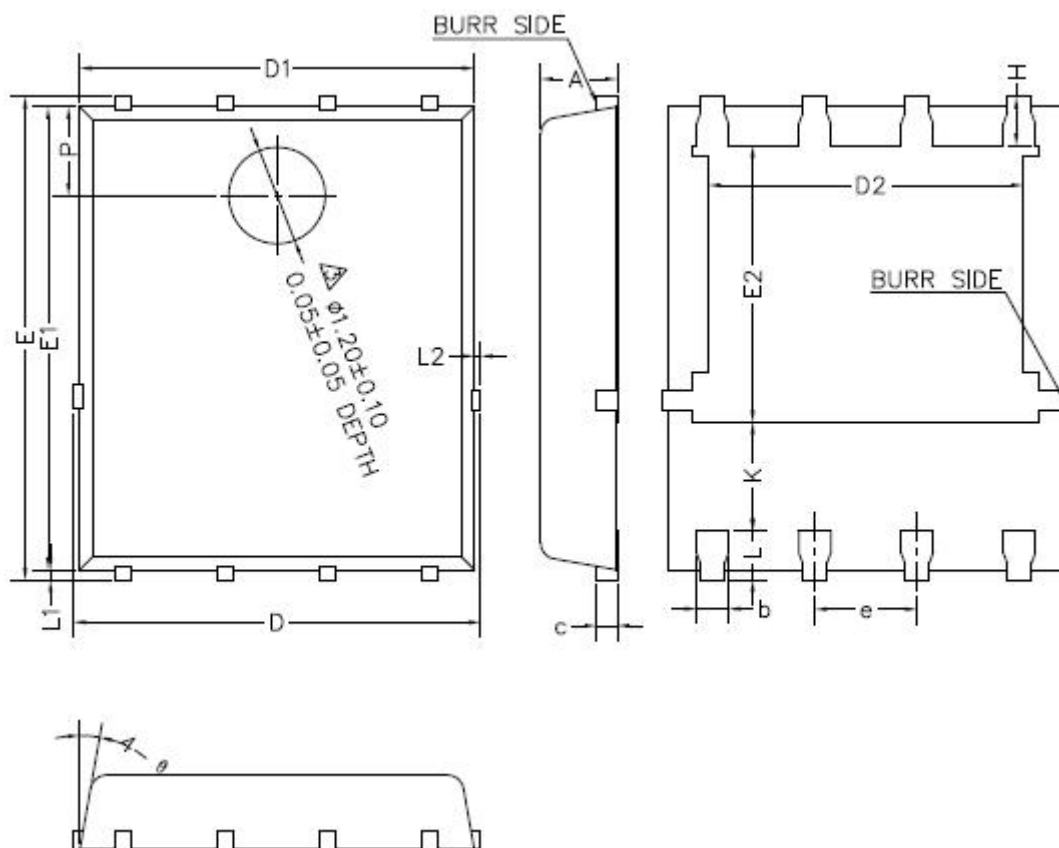
### 3. Unclaimed Inductive Switching Test Circuit & Waveforms





#### 4. Test Circuit and Waveform for Diode Characteristics



**Mechanical Dimension**
**PDFN5\*6-8 Unit: mm**


| Symbol | Dimensions(mm) |      |      |
|--------|----------------|------|------|
|        | Min.           | Typ. | Max. |
| A      | 0.90           | 1.10 | 1.20 |
| b      | 0.35           | 0.40 | 0.45 |
| c      | 0.21           | 0.25 | 0.34 |
| D      |                |      | 5.10 |
| D1     | 4.80           | 4.90 | 5.00 |
| D2     | 3.91           | 4.01 | 4.11 |
| e      | 1.17           | 1.27 | 1.37 |
| E      | 5.90           | 6.00 | 6.10 |
| E1     | 5.70           | 5.75 | 5.80 |
| E2     | 3.34           | 3.44 | 3.54 |
| H      | 0.51           | 0.61 | 0.71 |
| K      | 1.10           |      |      |
| L      | 0.51           | 0.61 | 0.71 |
| L1     | 0.06           | 0.13 | 0.20 |
| L2     |                |      | 0.10 |
| P      | 1.00           | 1.10 | 1.20 |
| θ      | 8°             | 10°  | 12°  |



Sanrise Technology Limited Company

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#### IMPORTANT NOTICE

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